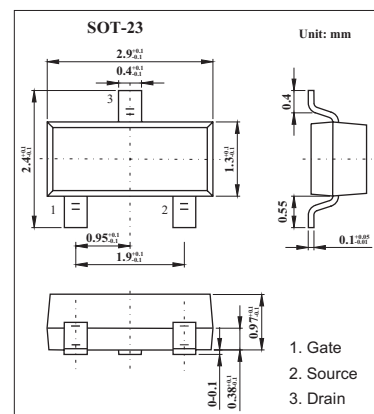
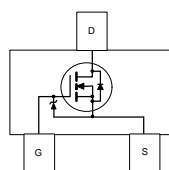


## Digital FET, N-Channel

### KDV303N

#### ■ Features

- 0.68 A, 25 V.  $R_{DS(ON)} = 0.45 \Omega @ V_{GS} = 4.5 \text{ V}$   
 $R_{DS(ON)} = 0.6 \Omega @ V_{GS} = 2.7 \text{ V}$ .
- Very low level gate drive requirements allowing direct operation in 3V circuits.  $V_{GS(th)} < 1.5 \text{ V}$ .
- Gate-Source Zener for ESD ruggedness.  
>6kV Human Body Model



#### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Drain to Source Voltage	$V_{DS}$	25	V
Gate to Source Voltage	$V_{GS}$	8	V
Drain Current- Continuous	$I_D$	0.68	A
Drain Current- pulse		2	A
Power Dissipation for Single Operation	$P_D$	0.35	W
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$
Thermal Resistance, Junction-to- Ambient	$R_{\theta JA}$	357	$^\circ\text{C/W}$

## KDV303N

## ■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V <sub>DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	25			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V			1	μA
		V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55°C			10	μA
Gate-Body Leakage Current, Forward	I <sub>GSSF</sub>	V <sub>GS</sub> = 8V, V <sub>DS</sub> = 0 V			100	nA
Gate-Body Leakage Current, Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> = -8 V, V <sub>DS</sub> = 0 V			-100	nA
Gate Threshold Voltage *	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	0.65	0.8	1.5	V
Static Drain-Source On-Resistance*	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.5A		0.33	0.45	Ω
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.2A, T <sub>J</sub> = 125°C		0.52	0.8	Ω
		V <sub>GS</sub> = 2.7V, I <sub>D</sub> = 0.2 A		0.44	0.6	Ω
On-State Drain Current *	I <sub>D(on)</sub>	V <sub>GS</sub> = 2.7 V, V <sub>DS</sub> = 5 V	0.5			A
Forward Transconductance *	g <sub>FS</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 0.5 A		1.45		S
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 10 V,		50		pF
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V,		28		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0 MHz		9		pF
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 6V, I <sub>D</sub> = 0.5A,		3	6	ns
Turn-On Rise Time	t <sub>r</sub>	V <sub>GS</sub> = 4.5V, R <sub>GEN</sub> = 50Ω		8.5	18	ns
Turn-Off Delay Time	t <sub>d(off)</sub>			17	30	ns
Turn-Off Fall Time	t <sub>f</sub>			13	25	ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 0.5A,		1.64	2.3	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 4.5V,		0.38		nC
Gate-Drain Charge	Q <sub>gd</sub>			0.45		nC
Maximum Continuous Drain-Source Diode Forward Current	I <sub>S</sub>				0.3	A
Drain-Source Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 0.5 A		0.83	1.2	V

\* Pulse Test: Pulse Width < 300μs, Duty Cycle < 2.0%.

# KDV303N

## Typical Characteristics

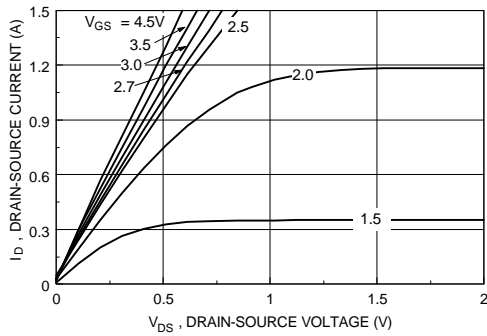


Figure 1. On-Region Characteristics.

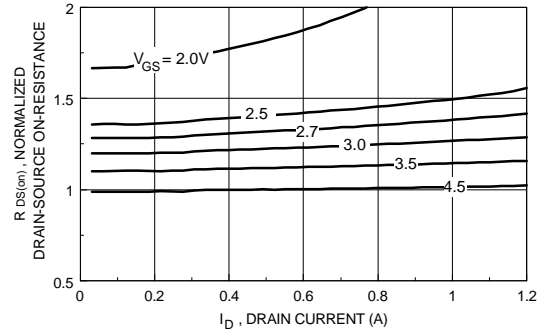


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

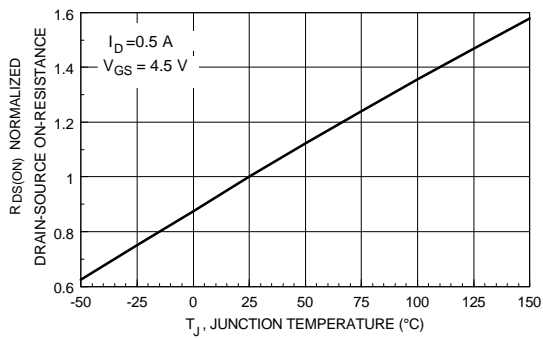


Figure 3. On-Resistance Variation with Temperature.

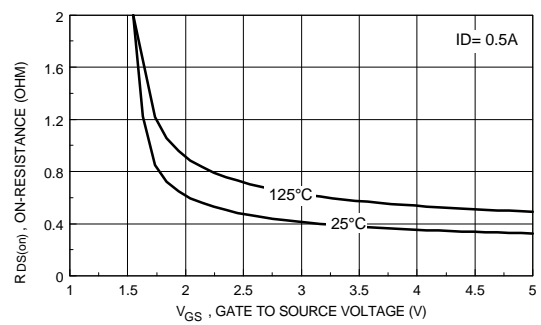


Figure 4. On Resistance Variation with Gate-To- Source Voltage.

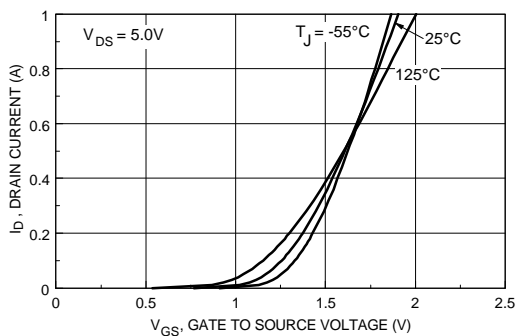


Figure 5. Transfer Characteristics.

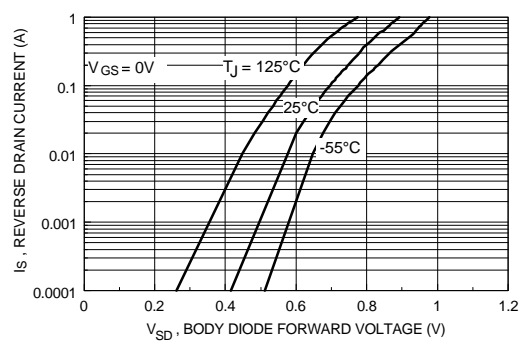


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

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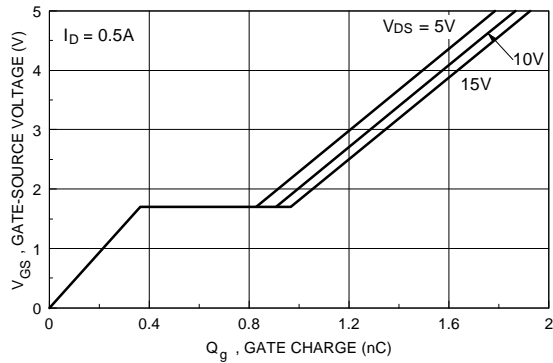


Figure 7. Gate Charge Characteristics.

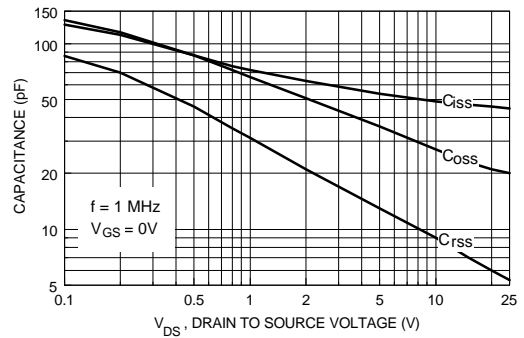


Figure 8. Capacitance Characteristics.

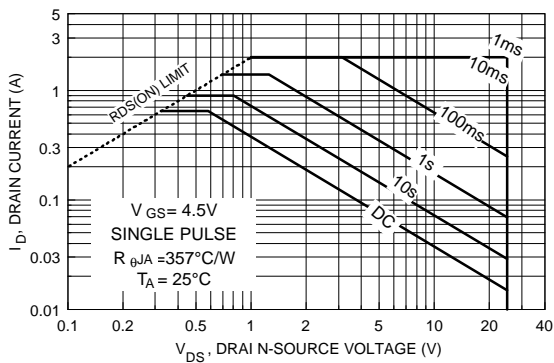


Figure 9. Maximum Safe Operating Area.

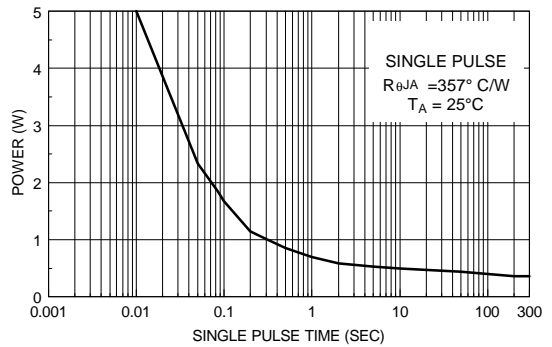


Figure 10. Single Pulse Maximum Power Dissipation.

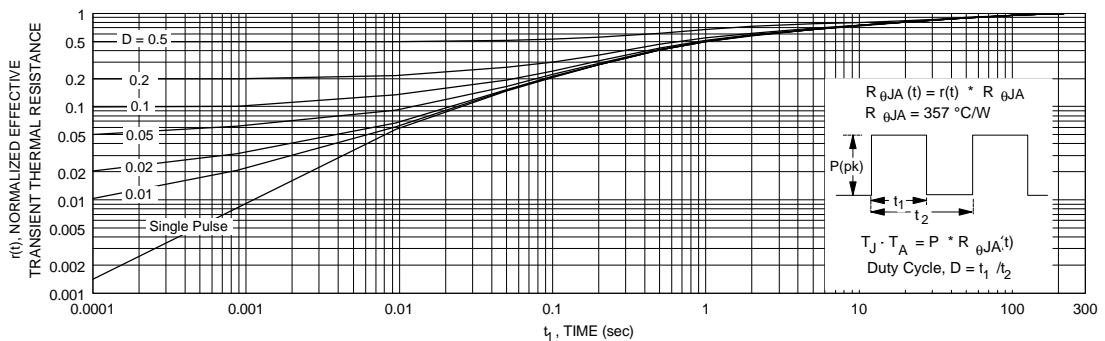


Figure 11. Transient Thermal Response Curve.